

## CT4000 Series has the Highest Heat Resistivity Among Organic Material.

### Strong Points

#### CT4112 Lower Curing Temperature Type (JCR for automobile electronics devices)

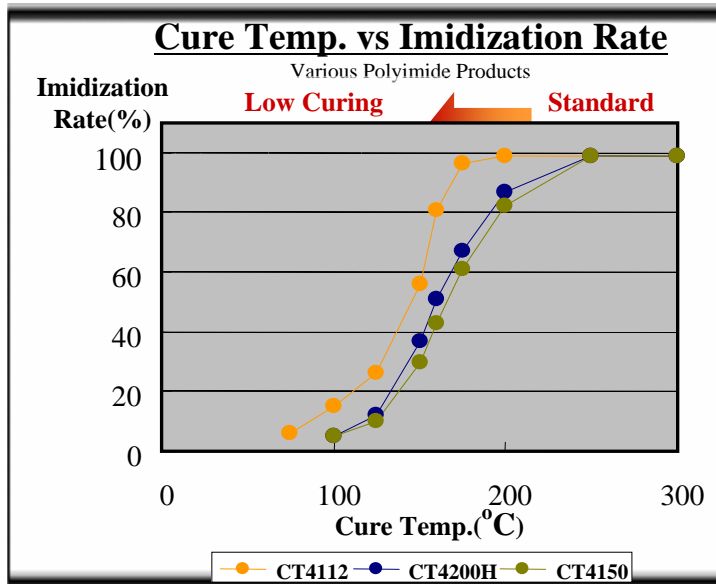
- 1) This can be Cured at Lower Curing Temperature (180 °C) Compared with a General Polyimide Resin.
- 2) Excellent Adhesive Property to Epoxy Resin, and There are a Lot of Sales Results in the JCR Application.

#### CT4200H Standard Type (Overcoat of the Semiconductor Device)

- 1) This is Standard Type in our Polyimide Products with High Heat Resistivity.
- 2) The Impurities are Extremely Little, and It is the Best for Overcoat of the Semiconductor Device.

#### CT4150 Heat Resistivity type (Heat Resistivity coating of Metal parts)

- 1) The Highest Products in terms of Heat Resistivity.
- 2) Suitable for SUS or Metal Coatings.



### Comparison of Heat Resistance

	Items	Unit	Epoxy	CT4112	CT4200H	CT4150
Heat resistance Test Items	Glass-Transition Temperature	°C	120	200	280	350 or More
	10% decomposition temperature	°C	300	540	560	600
	Coefficient of Thermal Expansion	1/°C	6*10 <sup>-5</sup>	7*10 <sup>-5</sup>	6*10 <sup>-5</sup>	2*10 <sup>-5</sup>
	Curing Temperature	°C	-	180	300	300

### Adhesion Strength to Epoxy Resin

